

ABSTRACT

In a method and an apparatus for mounting of electronic components onto a board, there are provided a head section (35) having a plurality of nozzles (12, 13) for sucking electronic components and a recognition camera (15) for recognizing a posture of sucked electronic component through its image and, a control component (1) for controlling the head section so that after the electronic components at a component feed section (30) are sucked by the nozzles, the sucked posture is image-recognized by the recognition camera and corrected, wherein a main controller (1) is provided with a mounting procedure selection routine (11) for selectively driving the head section while one board is subjected to mounting, according to a first mounting procedure whereby one component is sucked and the sucked component is mounted by one of the nozzles and a different component is sucked and the sucked component is mounted by the other of the nozzles and according to a second mounting procedure whereby electronic components sucked by two nozzles are consecutively mounted after one electronic component is sucked by one nozzle and the other electronic component is sucked by the other nozzle.